Material Declaration Report

PERICOM Semiconductor Corporation
www.pericom.com

Package Type:	TQFN 72L
Pericom Package Code:	ZL72(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	142.025
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	1/15/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	59.021	SPEL	Silica	60676-86-0	90.150	53.2074
			Phenol resin	Proprietary	3.500	2.0657
			Epoxy Resin-1	Proprietary	1.750	1.0329
			Epoxy Resin-2	Proprietary	1.750	1.0329
			Epoxy Resin-3	Proprietary	1.750	1.0329
			Others Non-hazardous Material	Proprietary	1.000	0.5902
			Carbon Black	1333-86-4	0.100	0.0590
LEADFRAME	66.754		Copper	7440-50-8	96.953	64.7201
			Iron	7439-89-6	2.350	1.5687
			Zinc	7440-66-6	0.111	0.0740
			Phosphorus	7723-14-0	0.065	0.0434
			Nickel	7440-02-0	0.473	0.3155
			Palladium	7440-05-3	0.041	0.0274
			Gold	7440-57-5	0.007	0.0049
SILICON DIE	4.016		Silicon (Si)	7440-21-3	99.192	3.9836
			Non-hazardous Metal	Proprietary	0.808	0.0324
DIE ATTACH EPOXY	6.913		Silver	7440-22-4	80.000	5.5304
			Epoxy Resin	9003-36-5	10.000	0.6913
			Diluent	26447-14-3	6.000	0.4148
			Hardener	620-92-8	3.500	0.2420
			Dicyandamide	461-58-5	0.500	0.0346
GOLD WIRE	5.321		Gold(Au)	7440-57-5	99.990	5.3205
			Impurities	-	0.010	0.0005

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.